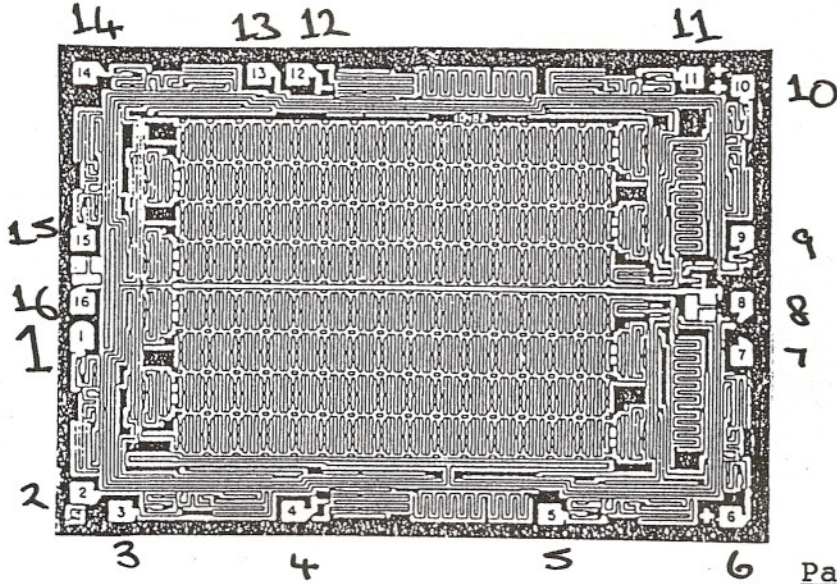




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>Pad</u>	<u>Function</u>	<u>Pad</u>	<u>Function</u>
1	Q16 _A	9	D _B
2	Q48 _A	10	Q32 _B
3	WE _A	11	Q64 _B
4	CL _A	12	CL _B
5	Q64 _A	13	WE _B
6	Q32 _A	14	Q48 _B
7	D _A	15	Q16 _B
8	V _{SS}	16	V _{DD}

Topside Metal: Al
Backside: Si
Backside Potential: Vdd
Mask Ref: 10482
Bond Pads (Mils): 4 x 4

APPROVED BY:
MFG: Harris

DIE SIZE (Mils): 144 X 107
THICKNESS: 20

DATE: 3/13/00
P/N: CD4517BH

DG 10.1.2
 Rev A 3-4-99